Performance Characteristics:

- Frequency range: 4GHz-8GHz
- Conversion gain: -14dB
- F0 isolation: 45dBc
- 3F0 Isolation: 45dBc
- 4F0 Isolation: 35dBc
- Input signal power: 15dBm
- Chip size: 1.5mm×0.69mm×0.1mm

Product Description:

CW-MP204 is a GaAs MMIC passive frequency multiplier, this type of frequency multiplier chip in the input power of 15dBm, conversion gain typical value of -14dB, the fundamental wave suppression to 45dBc, the third harmonic suppression to 45dBc, the fourth harmonic suppression to 35dBc, the typical input power of 15dBm.

Electrical parameters: (T_A=25℃,Pin=15dBm)

Indicators	Minimum	Typical value	Maximum value	Units
Input frequency	4-8			GHz
Output frequency	8-16			GHz
Conversion gain	-13	-14	-16	dB
Fundamental wave suppression	45	-	-	dBc
Third harmonic suppression	45	-	-	dBc
Fourth harmonic suppression	35	-	-	dBc

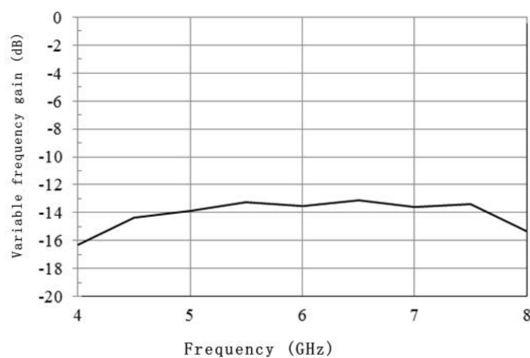
Use limiting parameters:

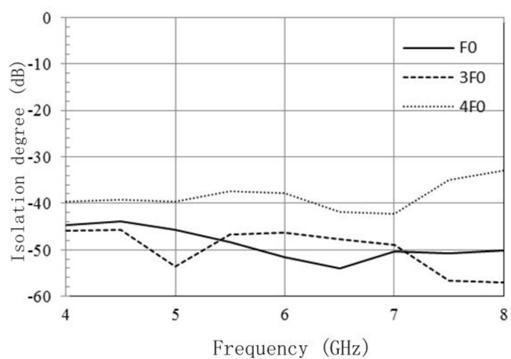
Maximum input power	27 dBm
Storage temperature	-65℃-150℃
Service temperature	-55℃-125℃

Typical curve:

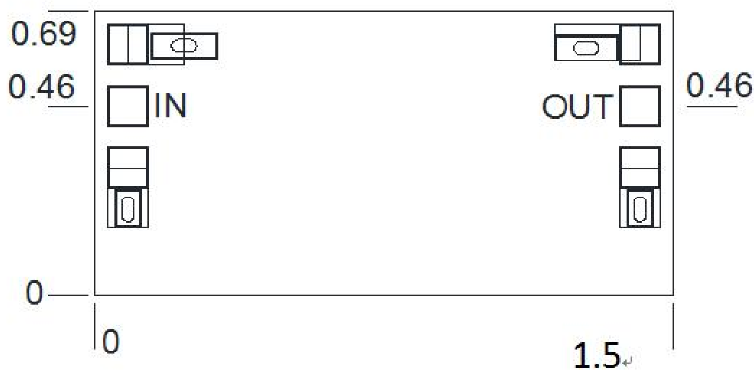
Isolation @Pin=15dBm

Conversion gain curve @Pin=15dBm

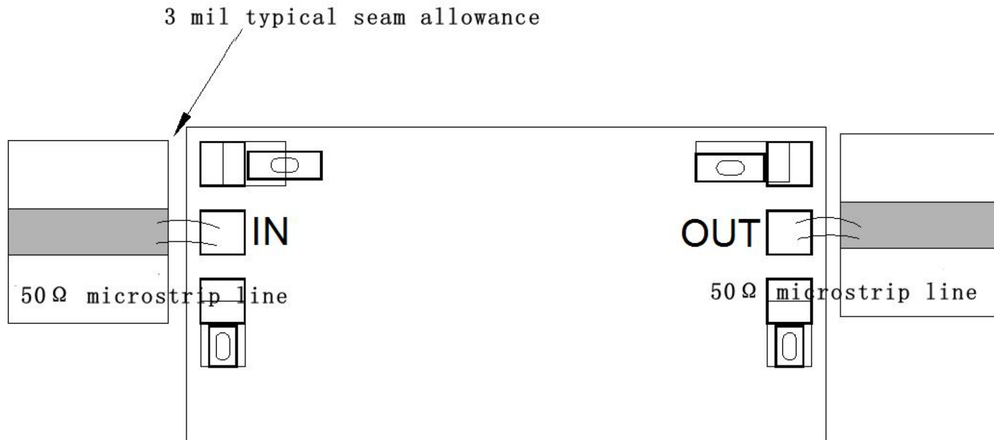




Size diagram: (unit mm)



Suggested assembly drawing:



Instructions:

Note: I/O has straight capacitance

Storage: The chip must be placed in a container with electrostatic protection and stored in a nitrogen environment.

Cleaning treatment: The bare chip must be operated and used in a purified environment. It is forbidden to use liquid cleaning agent to clean the chip.

Electrostatic protection: Strictly comply with the ESD protection requirements to avoid electrostatic damage to the components.

General operation: Use vacuum chuck or precision pointed tweezers to pick up the chip.Avoid touching the surface of the chip with tools or fingers during handling.

Mounting operation: The chip can be installed using AuSn solder eutectic welding or conductive adhesive bonding process.The mounting surface must be clean and flat.

Bonding operation: Input and output with 2 (recommended diameter of 25um gold wire) bonding wire, bonding wire length less than 250um is optimal.It is recommended to use the smallest possible ultrasonic energy.Bonding begins at the pressure point on the chip and ends at the package (or substrate).